



100% Material Declaration Data Sheet FG324

PK153 (v1.2) September 21, 2006

Material Declaration Data Sheet

Average Weight: 2.2251 g

Component	Substance Description	CAS# or Description	% of Component	Use in Product	Component Weight/ Substance Weight (in grams)	Component % of Total
Silicon Die					0.0257	1.16%
	Silicon	7440-21-3	100.00		0.0257	
Die Attach Material					0.0033	0.15%
	Silver	7440-22-4	78.00		0.0026	
	Resin	Trade Secret	22.00		0.0007	
Mold Compound					0.7632	34.30%
	Epoxy Resins	Trade Secret	12.00		0.0916	
	SiO2	60676-86-0	88.00	Filler	0.6716	
Laminate					0.8270	37.17%
	Laminate	Trade Secret	49.25		0.4073	
	Solder Mask	Trade Secret	7.70		0.0637	
	Copper	7440-50-8	40.91	Metal Layer	0.3383	
	Nickel	7440-02-0	1.79	Metal Layer	0.0148	
	Gold	7440-57-5	0.35	Metal Layer	0.0029	
Bond Wire					0.0135	0.61%
	Gold	7440-57-5	99.00		0.013347112	
	Silver	7440-22-4	0.0025		0.00000337	
	Copper	7440-50-8	0.0005		0.00000067	
	Iron	7439-89-6	0.0005		0.00000067	
	Calcium	7440-70-2	0.0020		0.00000270	
	Palladium	7440-05-3	0.9900		0.000133471	
	Magnesium	7439-95-4	0.0005		0.00000067	
Solder Balls					0.5924	26.62%
	Tin	7440-31-5	63.00		0.373212	
	Lead	7439-92-1	37.00		0.219188	

Revision History

The following table shows the revision history for this document.

Date	Revision	Revision
3/21/06	1.0	Initial release.
7/11/06	1.1	100% Material Declaration.
9/21/06	1.2	Updated component descriptions.